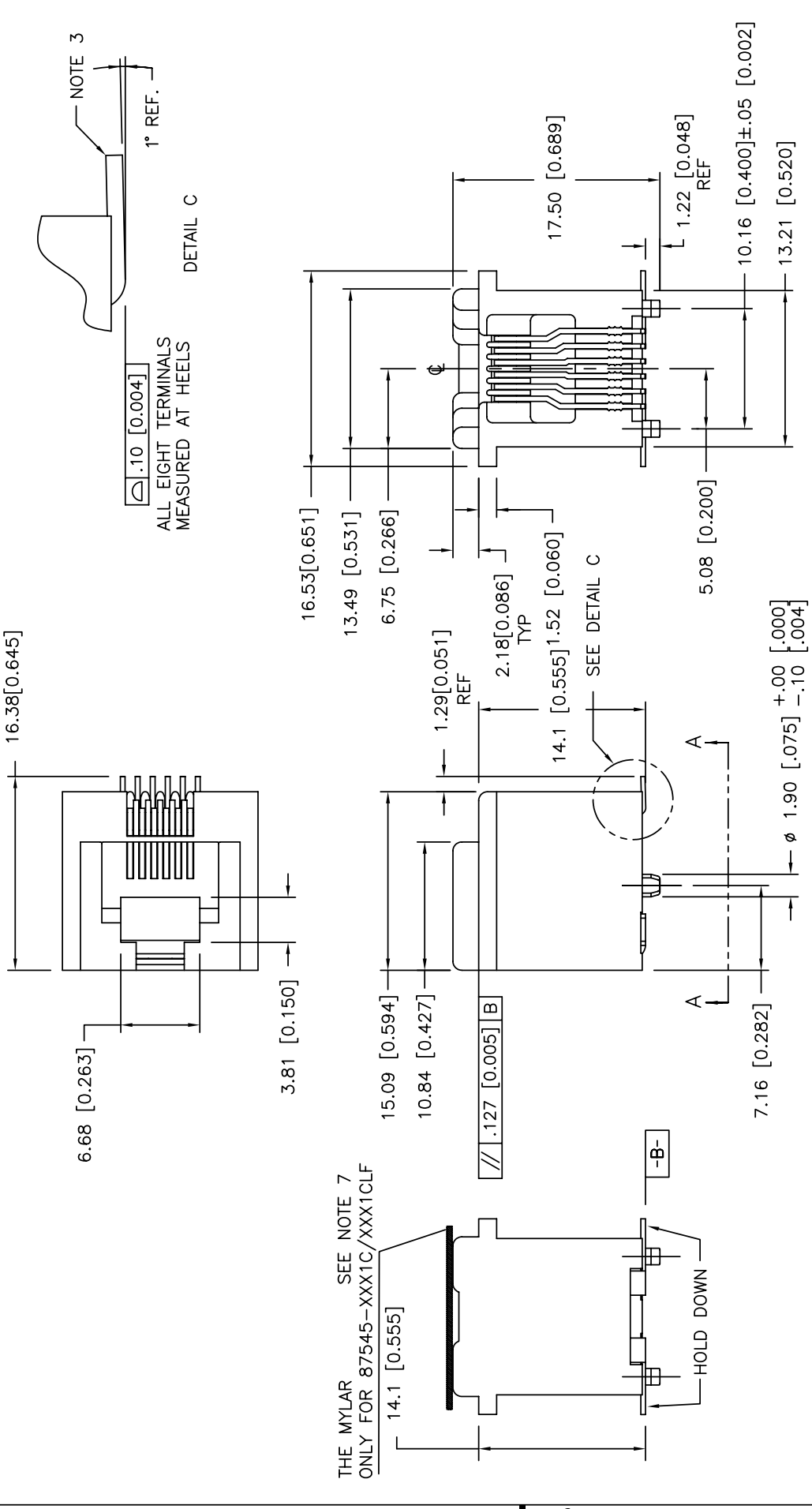
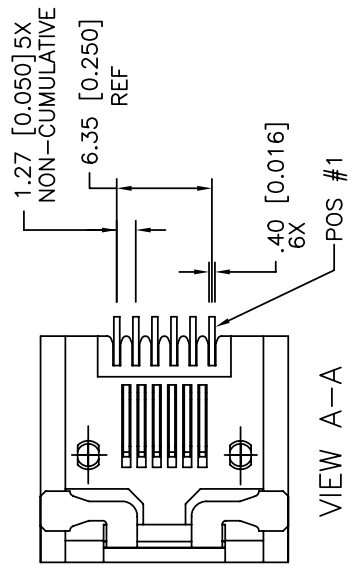


PRODUCT NO.
SEE TABLE



THE MYLAR SEE NOTE 7
ONLY FOR 87545-XXX1C/XXX1CLF



| | | | | | | | |
|-------------|----------|---------------------------------------|----------|-------------------------|--------------|---------------------------|----------|
| mat'l. code | | tolerances unless otherwise specified | | CUSTOMER COPY | | FCJ www.fcjconnect.com | |
| ltr | ecn no | dr | date | linear | projection | title | |
| J | V81474 | RGD | 9/15/96 | .XX±.13/.XXX±.005 | ⊕ | A-SMT ASSEMBLY VERT 6 POS | |
| K | V12666 | LP | 1/10/02 | .XXX±.051/.XXXX±.0020 | MM/INCH | product family | MOD JACK |
| L | N05-0035 | YS | 02/18/05 | 0° ±2° | scale | size | dwg no |
| M | N05-0142 | ZC | 6/2/05 | S.DUJESTERHOEFT 3/20/96 | 1:1 | code | 213 |
| N | N07-0217 | WG | 09/07/07 | Y.BELOPOLSKY 3/20/96 | | sheet | 1 of 2 |
| P | N08-0194 | SH | 09/08/08 | Y.BELOPOLSKY 7/8/96 | | 87545 | |
| sheet index | revision | N | N | appd | Y.BELOPOLSKY | A4 | |
| | sheet | 1 | 2 | | | | |

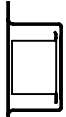

PRODUCT NO.

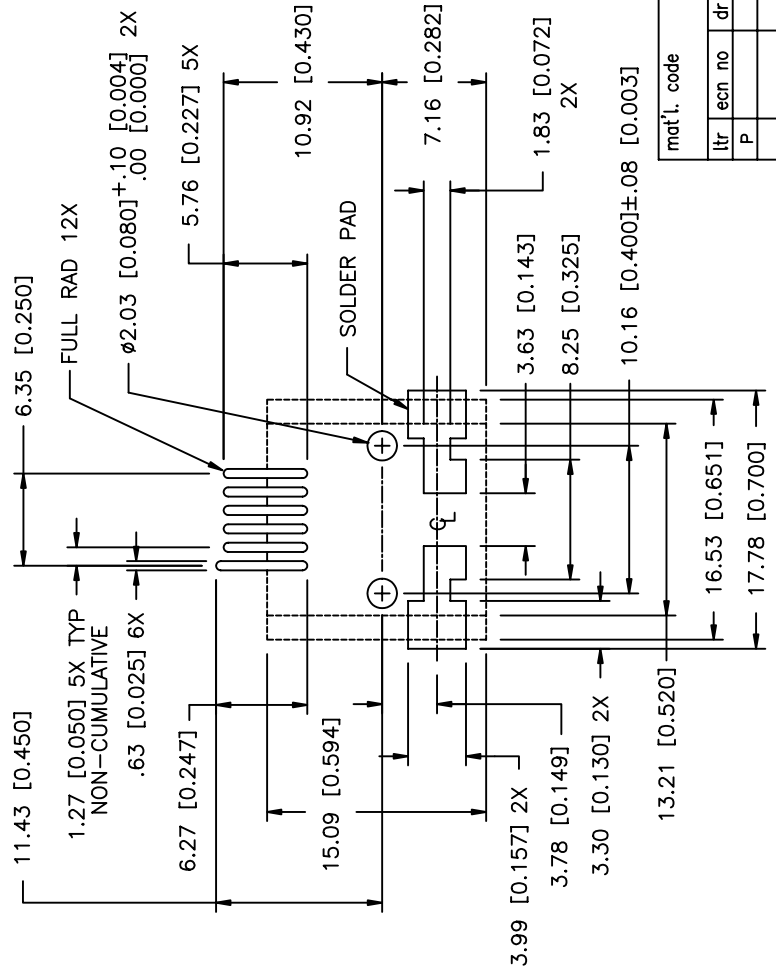
87545-XXXX 87545-XXXXLFL

| CONTACT PLATING OPTIONS | |
|-------------------------|------------|
| 1 = GXT .76µm [30µ"] | NOT TOOLED |
| 2 = GOLD 1.27µm [50µ"] | |
| 3 = PdNi .64µm [25µ"] | |
| 4 = GOLD .76µm [30µ"] | |

| TERMINAL LOADING OPTIONS | |
|--------------------------------|--|
| 1 = FULLY LOADED 6 POSITION | |
| 2 = POS 2,3,4,5 LOADED, 4 POS. | |

| COLOR | |
|-----------|--|
| 1 = BLACK | |

| PACKAGE OPTIONS | |
|-------------------------------|---|
| BLISTER PACKAGE (TAPE & REEL) |  |
| 1 = LOADED FACE UP | |
| BLISTER PACKAGE (TAPE & REEL) |  |
| 2 = LOADED FACE DOWN | NOT TOOLED |
| 3 = PACKAGED IN TUBES | NOT TOOLED |
| 4 = PACKAGED IN TRAYS | |





RECOMMENDED PC BOARD L/O

NOTES:

- 1 MATERIAL: HOUSING - THERMOPLASTIC V-0 CONTACT - PHOSPHOR BRONZE
- 2 PLATING: SOLDER TAILS - FOR 87545-XXXX : 2.54 µm [100 µIN] MIN. TIN LEAD OVER 2.54 µm [100 µIN] NICKEL FOR 87545-XXXXLF: 2 µm [80 µIN] MIN. PURE MATTE TIN OVER 1.27 µm [50 µIN] MIN. NICKEL FOR 87545-XXXX: 2.54 µm [100 µIN] MIN TIN LEAD OVER 2.54 µm [100 µIN] NICKEL FOR 87545-XXXXLF: 2µm [80 µIN] MIN. PURE TIN OVER 1.27 µm [50 µIN] MIN. NICKEL
- 3 MAX "TOE UP" AT TIP = 0.127 [0.005]
- 4 IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- 5 THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- 6 IF LF P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 7 APPLY THE MYLAR ON THE P/N 87545-XXX1 WITH SUFFIX "C" FOR PICKING UP. FOR INSTANCE 87545-4111CLF .



| tolerances unless otherwise specified | | CUSTOMER COPY | | title | |
|---------------------------------------|-----------------------|---------------|---|---------------------------|----------|
| linear | .XX±.13/.XXX±.005 | projection |  | A-SMT ASSEMBLY VERT 6 POS | |
| angles | 0° ±2° | MM/INCH |  | product family | MOD JACK |
| dr | S.DJESTERHOEF 3/20/96 | scale | 1:1 | size dwg no | A4 |
| enfr | Y.BELOPOLSKY 3/20/96 | code | | | 87545 |
| chr | Y.BELOPOLSKY 7/8/96 | sheet | | | 2 of |
| appd | Y.BELOPOLSKY 7/8/96 | sheet | | | |
| sheet index | revision sheet | | | | |

mat'l. code

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STATUS: **Released** 2.6 P. 03, 2004

PDM: Rev:P

ACAD

1 | 2

